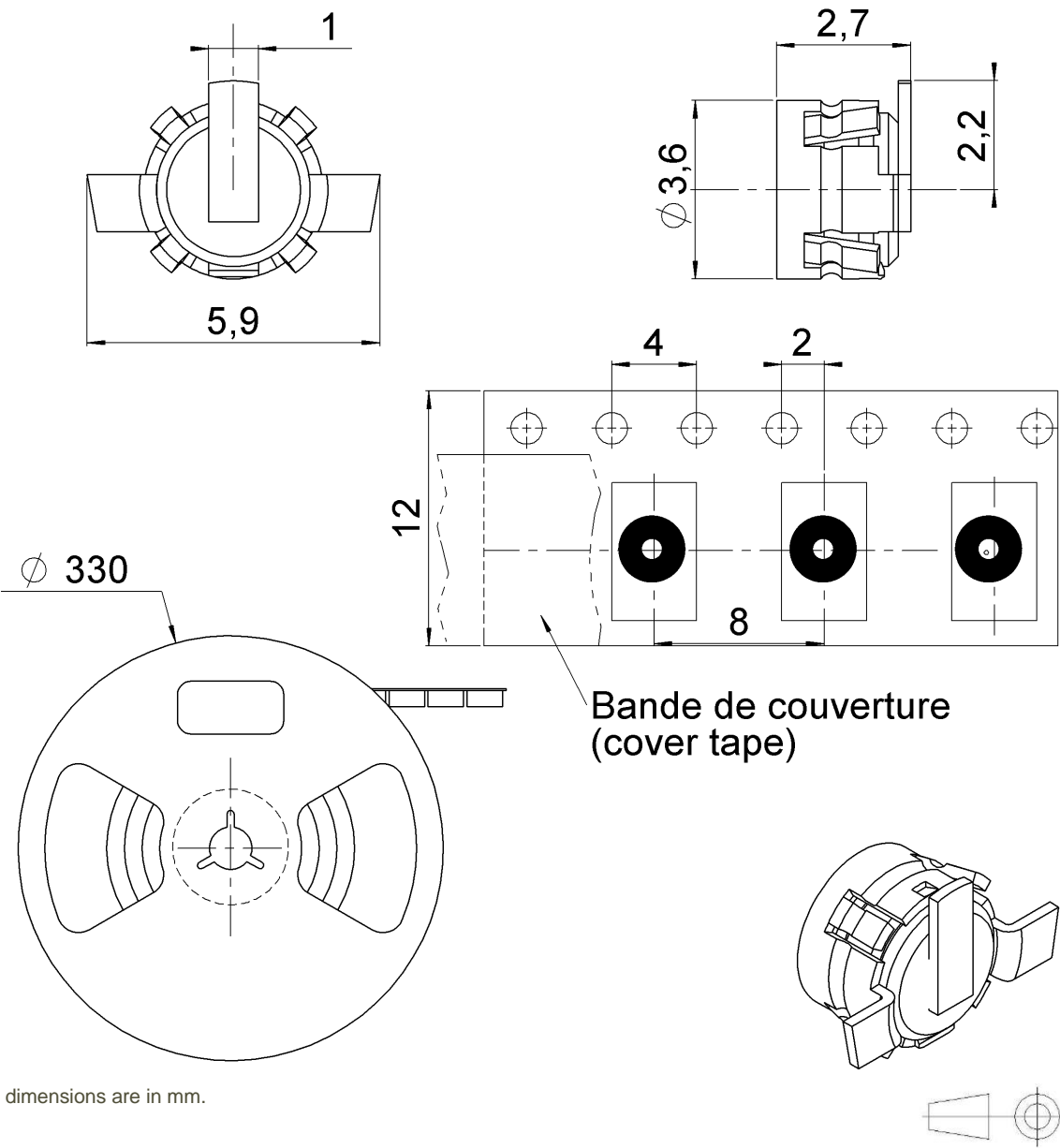


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COMPONENTS	MATERIALS	PLATING (µm)
Body	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Center contact	BRASS	GOLD 0.2 OVER NICKEL 2
Outer contact	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Insulator	PTFE	
Gasket	-	
Others parts	-	
-	-	
-	-	

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PACKAGING

Standard	Unit	Other
3000	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-8	GHz
VSWR	1.10	+	0,0500 x F(GHz) Maxi
Insertion loss		0.20	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz) dB Maxi
Voltage rating		170	Veff Maxi
Dielectric withstanding voltage		500	Veff mini
Insulation resistance		5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		NA	N mini
Axial force – Opposite end		NA	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		NA	N.cm
Panel nut		NA	N.cm
Mating life		500	Cycles mini
Weight		0,1000	g

ENVIRONMENTAL

Operating temperature	-55/+100	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

accouplt : 18Nmax / desacc. : 7Nmin

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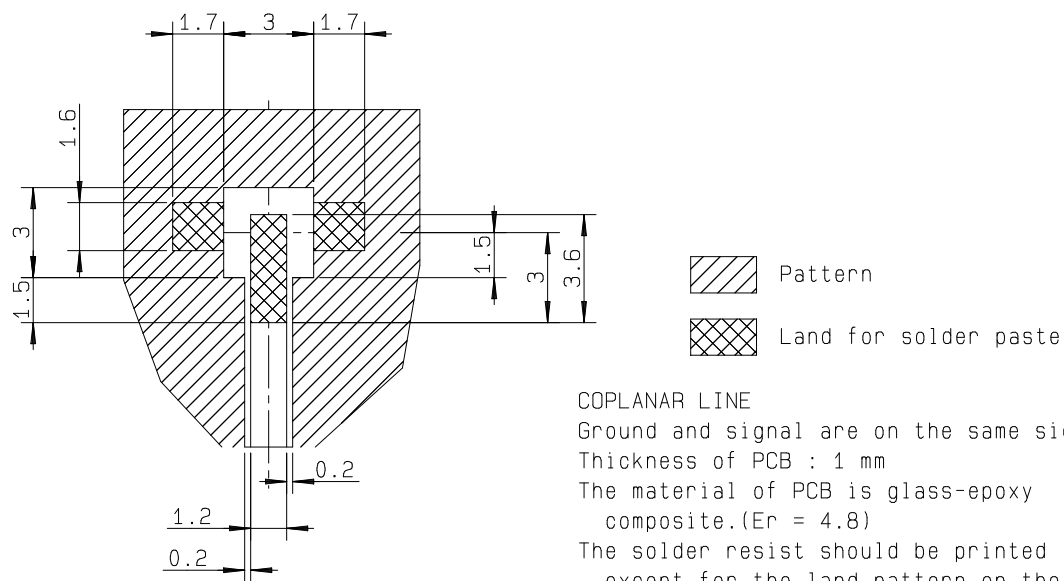
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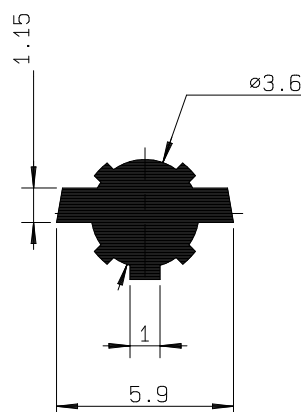
MMT SERIES - INFORMATION

ALL DIMENSIONS IN MM



ALL DIMENSIONS IN MM

SHADOW OF MMT RECEPTACLE FOR VIDEO CAMERA



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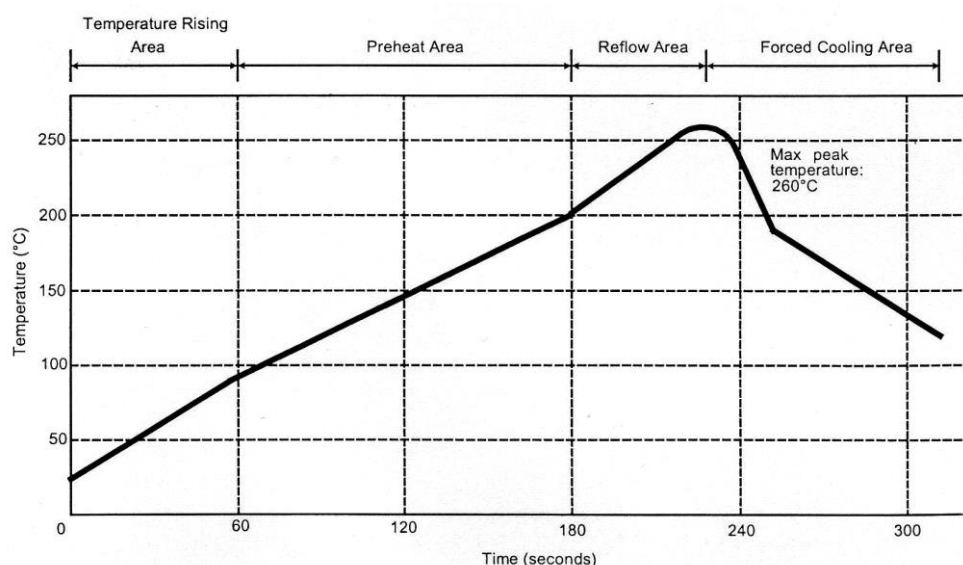
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SOLDER PROCEDURE OF MMT RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1 – Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application.
We recommend a Low Residue Solid Flux.
We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean.
- 2 – Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type.
A video camera is recommended for positioning of the component. (see page 3)
Adhesive agents must not be used on the receptacle.
- 3 – Soldering by infra-red reflow.
Below, please find the typical profile to use.
- 4 – Cleaning of printed circuit boards
- 5 – Verification of solder joints and position of the component by visual inspection



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec